

Vishay Siliconix



N-Channel 30 V (D-S) MOSFET

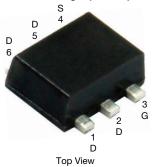
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) MAX.	I <sub>D</sub> (A)	Q <sub>g</sub> (TYP.)		
	0.142 at V <sub>GS</sub> = 10 V	1.02			
30	0.154 at V <sub>GS</sub> = 4 V	0.98	1.5		
	0.195 at V <sub>GS</sub> = 2.5 V	0.87			

#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> tested
- Typical ESD performance 1400 V
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

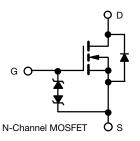






#### **APPLICATIONS**

· Load switch for portable devices



#### Marking Code: D **Ordering Information:**

Si1078X-T1-GE3 (lead (Pb)-free and halogen-free)

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	$V_{DS}$	30			
Gate-Source Voltage		$V_{GS}$	± 12	V	
Continuous Dunis Comment /T 150 °C\ 3	T <sub>A</sub> = 25 °C		1.02 <sup>a, b</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C	I <sub>D</sub>	0.82 <sup>a, b</sup>		
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	6	A	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.2 <sup>a, b</sup>	7	
Mariana Danier Discipation	T <sub>A</sub> = 25 °C		0.24 <sup>a, b</sup>	14/	
Maximum Power Dissipation	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.15 <sup>a, b</sup>	W	
Operating Junction and Storage Temperature Ra	ange	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYPICAL	MUMIXAM	UNIT		
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 5 s	R <sub>thJA</sub>	440	530	°C/W	
Maximum sunction-to-Ambient	Steady State		540	650	C/ VV	

#### **Notes**

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 650 °C/W.



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			1		1000		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	30	_	_	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$		-	36.7	-		
V <sub>GS(th)</sub> Temperature Coefficient	ΔV <sub>GS(th)</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA	_	-2.8	-	mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6	-	1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-	-	± 20	1	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1	- - μA	
7. 0. 11. 5. 0	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	-	-	10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	6	-	-	Α	
	-D(OII)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A	-	0.118	0.142	<u> </u>	
Drain-Source On-State Resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 1 A	-	0.128	0.154	Ω	
	-(-,/	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 0.5 A	-	0.150	0.195	1	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 1 A	-	5.5	-	S	
Dynamic <sup>b</sup>						L	
Input Capacitance	C <sub>iss</sub>		-	110	-		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	21	-	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	11	-		
	Qg	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A	-	3	6	nC	
Total Gate Charge			-	1.5	3		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1 \text{ A}$	-	0.2	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	0.42	-		
Gate Resistance	$R_g$	f = 1 MHz	1.04	5.2	5.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		-	8	16		
Rise Time	t <sub>r</sub>	$t_r$ $V_{DD} = 15 \text{ V}, R_L = 18.9 \Omega$		25	38	]	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	23	35		
Fall Time	t <sub>f</sub>		-	23	35		
Turn-On Delay Time	t <sub>d(on)</sub>		-	5	10	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 18.9 \Omega$	-	23	35	]	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.8 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20	]	
Fall Time	t <sub>f</sub>		-	35	53		
Drain-Source Body Diode Characteristics							
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>		-	-	6	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 0.8 A	-	0.75	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	12	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 2 A dl/dt = 100 A/vo	-	4	8	nC	
Reverse Recovery Fall Time	ta	I <sub>F</sub> = 2 A, dl/dt = 100 A/μs	-	7	_	ne	
Reverse Recovery Rise Time t <sub>b</sub>			-	5	-	- ns	

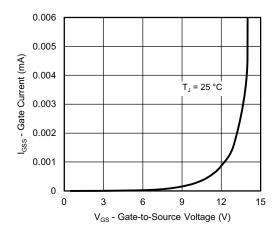
#### **Notes**

- a. Pulse test; pulse width  $\leq$  100 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

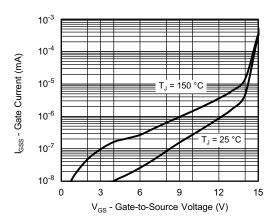
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



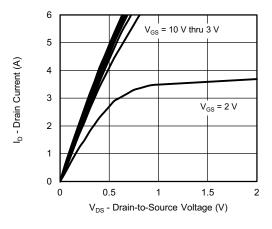
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



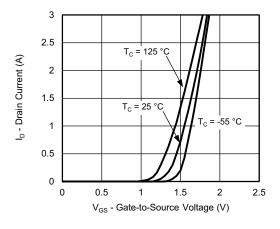
Gate Current vs. Gate-to-Source Voltage



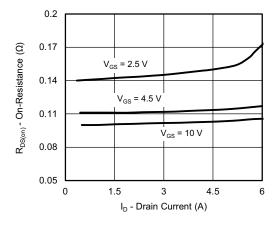
Gate Current vs. Gate-to-Source Voltage



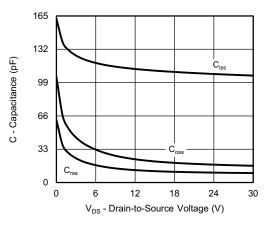
**Output Characteristics** 



**Transfer Characteristics** 



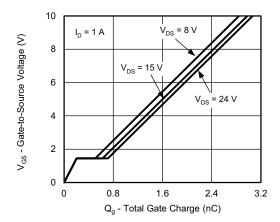
On-Resistance vs. Drain Current



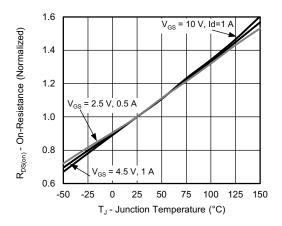
Capacitance



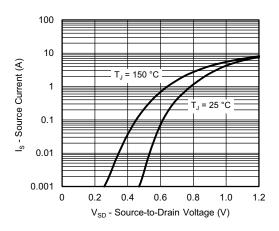
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



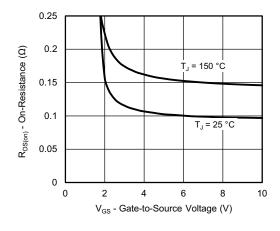
**Gate Charge** 



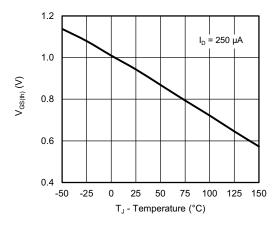
On-Resistance vs. Junction Temperature



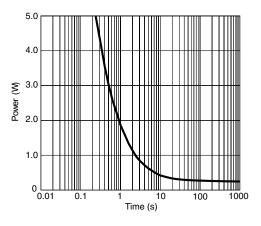
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



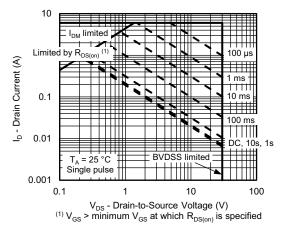
**Threshold Voltage** 



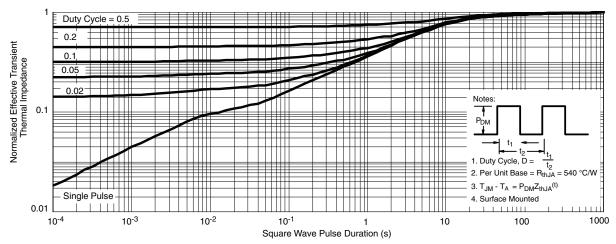
Single Pulse Power, Junction-to-Ambient



### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient

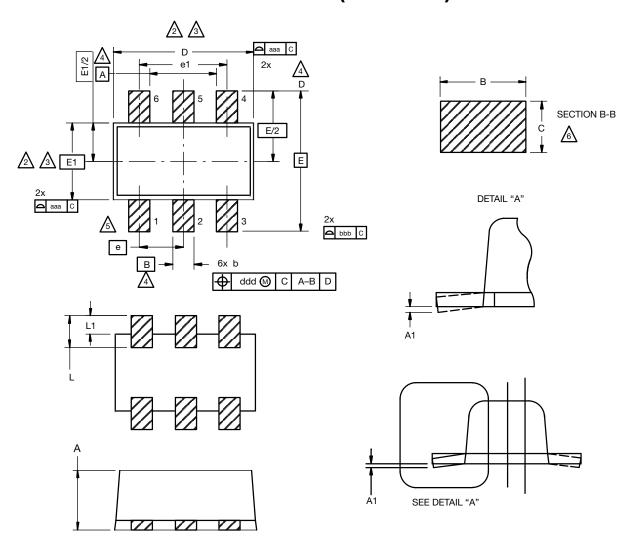


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?68549">www.vishay.com/ppg?68549</a>.



## **SC-89 6-Leads (SOT-563F)**



#### Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

 $\Delta$ Terminal numbers are shown for reference only.

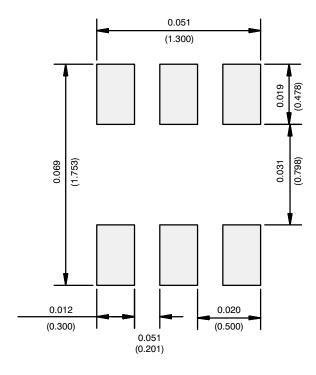
These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
Α	0.56	0.58	0.60		
A1	0	0.02	0.10		
b	0.15	0.22	0.30		
С	0.10	0.14	0.18		
D	1.50	1.60	1.70		
E	1.50	1.60	1.70		
E1	1.15	1.20	1.25		
е	0.45	0.50	0.55		
e1	0.95	1.00	1.05		
L	0.25	0.35	0.50		
L1	0.10	0.20	0.30		
C14-0439-Rev. C, 11-Aug-14 DWG: 5880					

Revision: 11-Aug-14 1 Document Number: 71612



#### **RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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